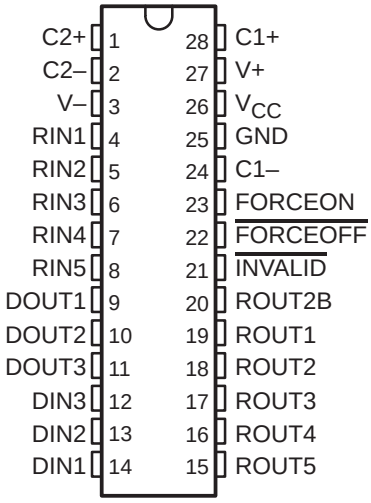
SLLS350A – APRIL 1999 – REVISED JUNE 1999

- **Single-Chip and Single-Supply Interface for IBM™ PC/AT™ Serial Port**
- **Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards**
- **Operate With 3-V to 5.5-V V_{CC} Supply**
- **Always-Active Noninverting Receiver Output (ROUT2B)**
- **Designed to Operate up to 512 kbit/s**
- **Low Standby Current . . . 1 μA Typical**
- **External Capacitors . . . 4 × 0.1 μF**
- **Accept 5-V Logic Input With 3.3-V Supply**
- **Designed to be Interchangeable With Maxim MAX3243C and MAX3243E**
- **Serial-Mouse Driveability**
- **RS-232 Bus-Pin ESD Protection Exceeds ±15-kV Using Human-Body Model (HBM)**
- **Applications**
  - **Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages**

DB, DW, OR PW PACKAGE
(TOP VIEW)



PRODUCT PREVIEW

description

The MAX3243 devices consist of three line drivers, five line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin-to-pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector, and meet the requirements of TIA/EIA-232-F. This combination of drivers and receivers matches that needed for the typical serial port used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, these devices include an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the devices are powered down. The devices operate at data signaling rates up to 512 kbit/s, and a maximum of 30-V/μs driver output slew-rate.

description (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If $\overline{\text{FORCEOFF}}$ is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 μA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high, and should be done when driving a serial mouse. With auto-powerdown enabled, the devices are activated automatically when a valid signal is applied to any receiver input. The $\overline{\text{INVALID}}$ output is used to notify the user if an RS-232 signal is present at any receiver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V or has been between –0.3 V and 0.3 V for less than 30 μs. $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltages are between –0.3 V and 0.3 V for more than 30 μs. Refer to Figure 4 for receiver input levels.

The MAX3243C is characterized for operation over the temperature range of 0°C to 70°C. The MAX3243I is characterized for operation over the temperature range of –40°C to 85°C.

Function Tables

EACH DRIVER

INPUTS				OUTPUT	DRIVER STATUS
DIN	FORCEON	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL	DOUT	
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

H = high level, L = low level, X = irrelevant, Z = high impedance

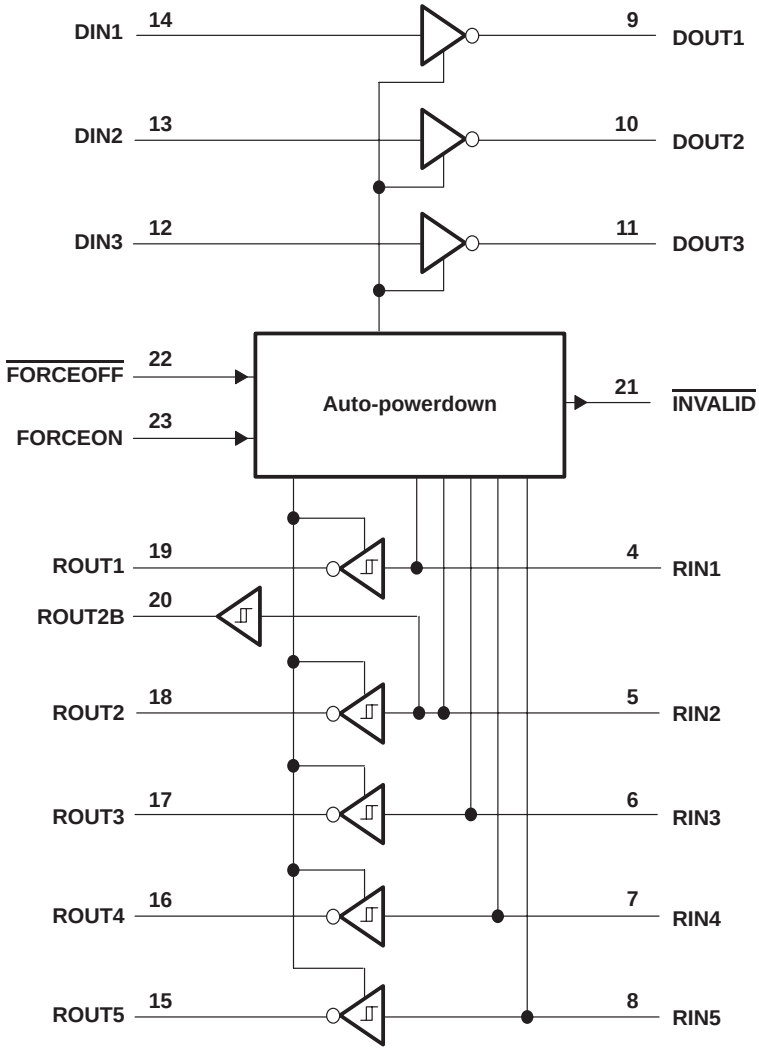
EACH RECEIVER

INPUTS				OUTPUTS		RECEIVER STATUS
RIN2	RIN1, RIN3–RIN5	$\overline{\text{FORCEOFF}}$	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	
L	X	L	X	L	Z	Powered off while ROUT2B is active
H	X	L	X	H	Z	
L	L	H	Yes	L	H	Normal operation with auto-powerdown disabled/enabled
L	H	H	Yes	L	L	
H	L	H	Yes	H	H	
H	H	H	Yes	H	L	
Open	Open	H	No	L	H	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

PRODUCT PREVIEW

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . –0.3 V to 6 V
Positive output supply voltage, V+ (see Note 1) . . . . . –0.3 V to 7 V
Negative output supply voltage, V– (see Note 1) . . . . . 0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1) . . . . . 13 V
Input voltage range, V_I: Driver ($\overline{\text{FORCEOFF}}$, FORCEON) . . . . . –0.3 V to 6 V
Receiver . . . . . –25 V to 25 V
Output voltage range, V_O: Driver . . . . . –13.2 V to 13.2 V
Receiver ($\overline{\text{INVALID}}$) . . . . . –0.3 V to V_{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Note 2): DB package . . . . . TBD°C/W
DW package . . . . . 78°C/W
PW package . . . . . TBD°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3 and Figure 5)

			MIN	NOM	MAX	UNIT
Supply voltage	V_{CC} = 3.3 V		3	3.3	3.6	V
	V_{CC} = 5 V		4.5	5	5.5	V
Driver and control high-level input voltage, V_{IH}	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 3.3 V	2			V
		V_{CC} = 5 V	2.4			
Driver and control low-level input voltage, V_{IL}	DIN, $\overline{\text{FORCEOFF}}$, FORCEON				0.8	V
Receiver input voltage, V_I			–25		25	V
Operating free-air temperature, T_A	MAX3243C		0		70	°C
	MAX3243I		–40		85	

NOTE 3: Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

PARAMETER		TEST CONDITIONS		MIN	TYP‡	MAX	UNIT
I_I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON			±0.01	±1	µA
I_{CC}	Supply current	Auto-powerdown disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V_{CC}		0.3	1	mA
		Powered off	No load, $\overline{\text{FORCEOFF}}$ at GND		1	10	µA
		Auto-powerdown enabled	No load, $\overline{\text{FORCEOFF}}$ at V_{CC}, FORCEON at GND, All RIN are open or grounded		1	10	

‡ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.
NOTE 3. Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	All DOUT at R_L = 3 kΩ to GND			5	5.4		V
		DIN1 = DIN2 = GND, DIN3 = V_{CC}, 3-kΩ load to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA			5			
V_{OL}	Low-level output voltage	All DOUT at R_L = 3 kΩ to GND			–5	–5.4		V
		DIN1 = DIN2 = GND, DIN3 = V_{CC}, 3-kΩ load to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA			–5			
I_{IH}	High-level input current	$V_I = V_{CC}$				±0.01	±1	µA
I_{IL}	Low-level input current	V_I at GND				±0.01	±1	µA
I_{OS}	Short-circuit output current‡	V_{CC} = 3.6 V,	V_O = 0 V			±35	±60	mA
		V_{CC} = 5.5 V,	V_O = 0 V					
r_o	Output resistance	V_{CC}, V+, and V– = 0 V,	V_O = ±2 V		300	10M		Ω
I_{off}	Output leakage current	$\overline{\text{FORCEOFF}}$ = GND,	V_O = ±12 V,	V_{CC} = 0 to 5.5 V			±25	µA

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.
‡ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.
NOTE 3. Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
	Maximum data rate	C_L = 1000 pF, One DOUT switching,	R_L = 3 kΩ, See Figure 1		512			kbit/s
$t_{sk(p)}$	Pulse skew§	C_L = 150 pF to 2500 pF,	R_L = 3 kΩ to 7 kΩ			100		ns
SR(tr)	Slew rate, transition region (see Figure 1)	V_{CC} = 3.3 V, R_L = 3 kΩ to 7 kΩ	C_L = 150 pF to 1000 pF		6		30	V/µs
			C_L = 150 pF to 2500 pF		4		30	

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.
§ Pulse skew is defined as $|t_{PLH} - t_{PHL}|$.
NOTE 3. Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

PRODUCT PREVIEW

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = –1 mA	V_{CC} – 0.6 V	V_{CC} – 0.1 V		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6 mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 3.3 V		1.6	2.4	V
		V_{CC} = 5 V		1.9	2.4	
$V_{IT–}$	Negative-going input threshold voltage	V_{CC} = 3.3 V	0.6	1.1		V
		V_{CC} = 5 V	0.8	1.4		
V_{hys}	Input hysteresis ($V_{IT+} – V_{IT–}$)			0.5		V
I_{off}	Output leakage current (except ROUT2B)	$\overline{\text{FORCEOFF}}$ = 0 V		±0.05	±10	µA
r_i	Input resistance	V_I = ±3 V to ±25 V	3	5	7	kΩ

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.
NOTE 3. Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 150 pF, See Figure 2		150		ns
t_{PHL}	Propagation delay time, high- to low-level output			150		ns
t_{en}	Output enable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 3		200		ns
t_{dis}	Output disable time			200		ns
$t_{sk(p)}$	Pulse skew‡	See Figure 2		50		ns

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.
‡ Pulse skew is defined as $|t_{PLH} – t_{PHL}|$.
NOTE 3. Test conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

PRODUCT PREVIEW

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{T+(VALID)}$	Receiver input threshold for $\overline{\text{INVALID}}$ high-level output voltage	$\overline{\text{FORCEON}}$ = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}			2.7	V
$V_{T-(VALID)}$	Receiver input threshold for $\overline{\text{INVALID}}$ high-level output voltage	$\overline{\text{FORCEON}}$ = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	–2.7			V
$V_{T(INVALID)}$	Receiver input threshold for $\overline{\text{INVALID}}$ low-level output voltage	$\overline{\text{FORCEON}}$ = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	–0.3		0.3	V
V_{OH}	$\overline{\text{INVALID}}$ high-level output voltage	I_{OH} = –1 mA, FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}	V_{CC} – 0.6			V
V_{OL}	$\overline{\text{INVALID}}$ low-level output voltage	I_{OL} = 1.6 mA, FORCEON = GND, $\overline{\text{FORCEOFF}}$ = V_{CC}			0.4	V

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

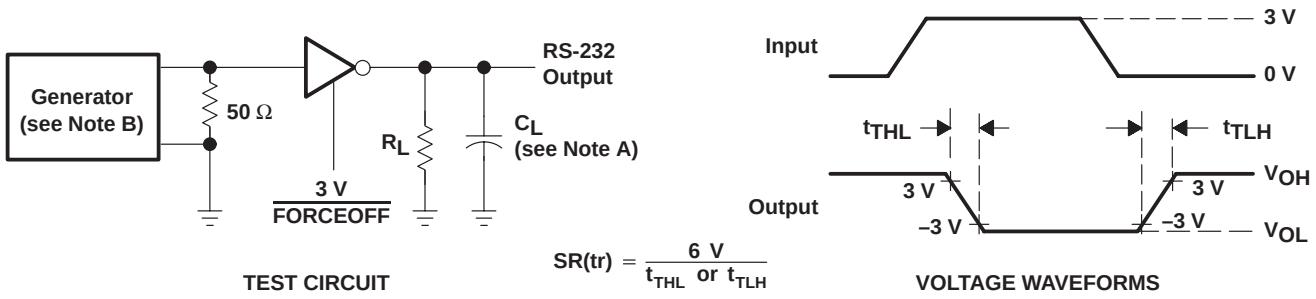
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

PARAMETER		MIN	TYP†	MAX	UNIT
t_{VALID}	Propagation delay time, low- to high-level output		1		µs
$t_{INVALID}$	Propagation delay time, high- to low-level output		30		µs
t_{en}	Receiver and driver output enable time		100		µs

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

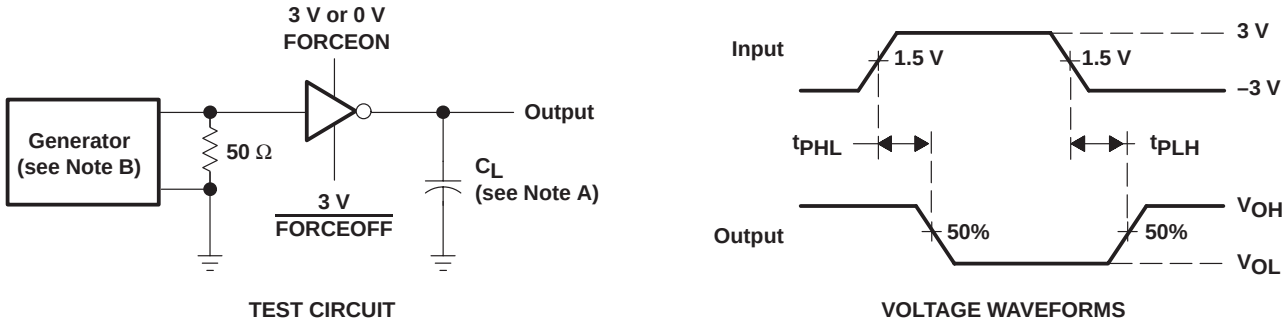
PRODUCT PREVIEW

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 1. Driver Slew Rate

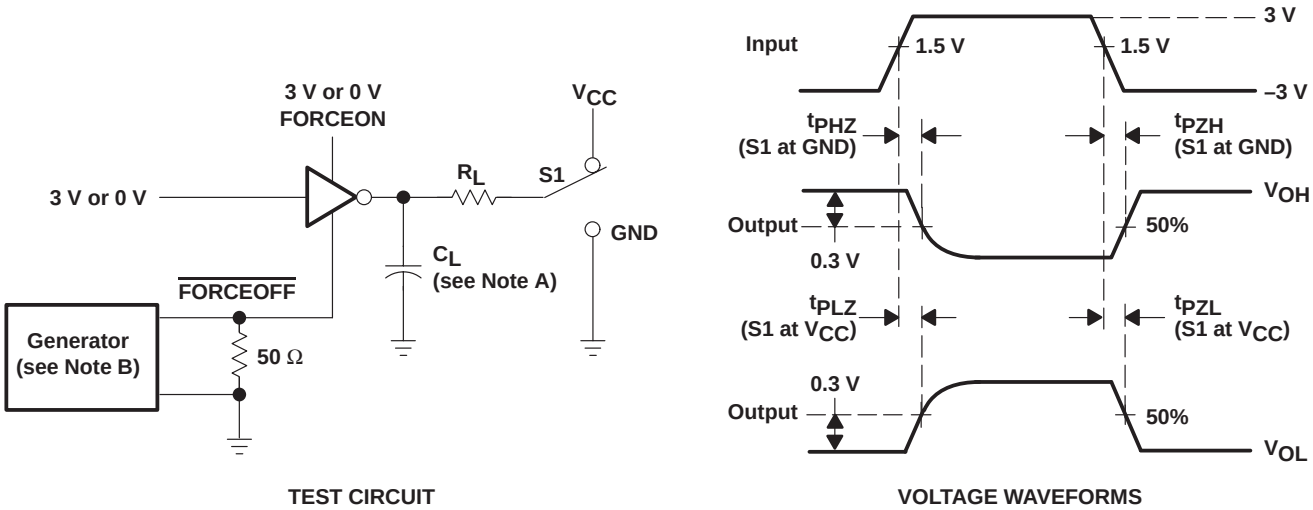


NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 512 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 2. Receiver Propagation Delay Times

PRODUCT PREVIEW

PARAMETER MEASUREMENT INFORMATION



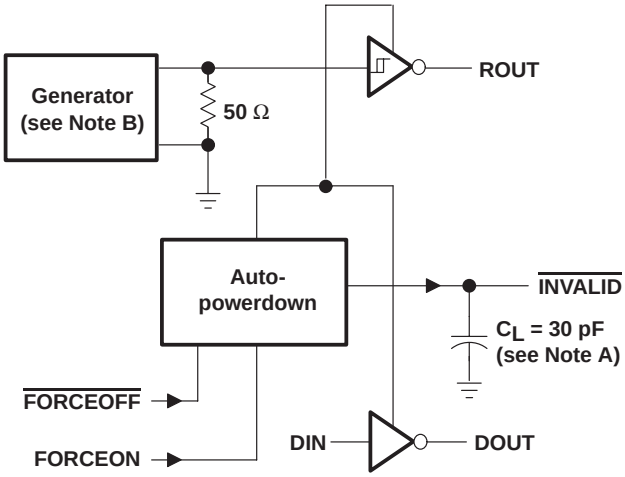
TEST CIRCUIT **VOLTAGE WAVEFORMS**

NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 512 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.
C. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
D. t_{PZL} and t_{PZH} are the same as t_{en}.

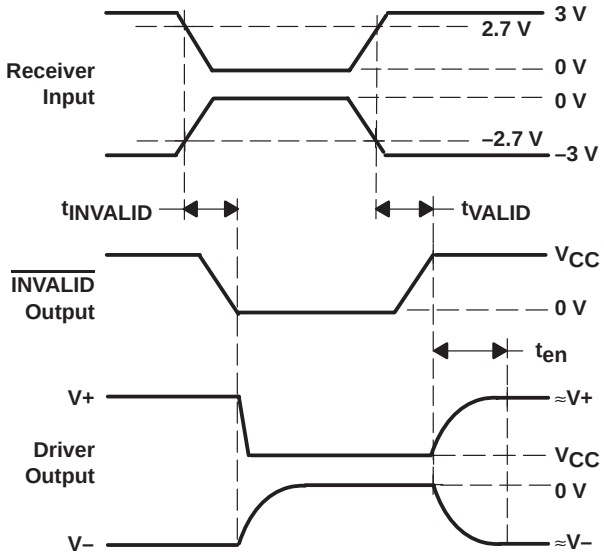
Figure 3. Receiver Enable and Disable Times

PRODUCT PREVIEW

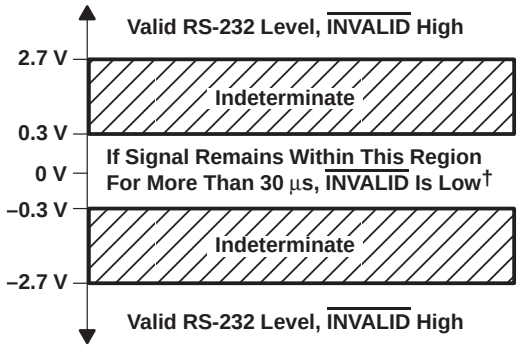
PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

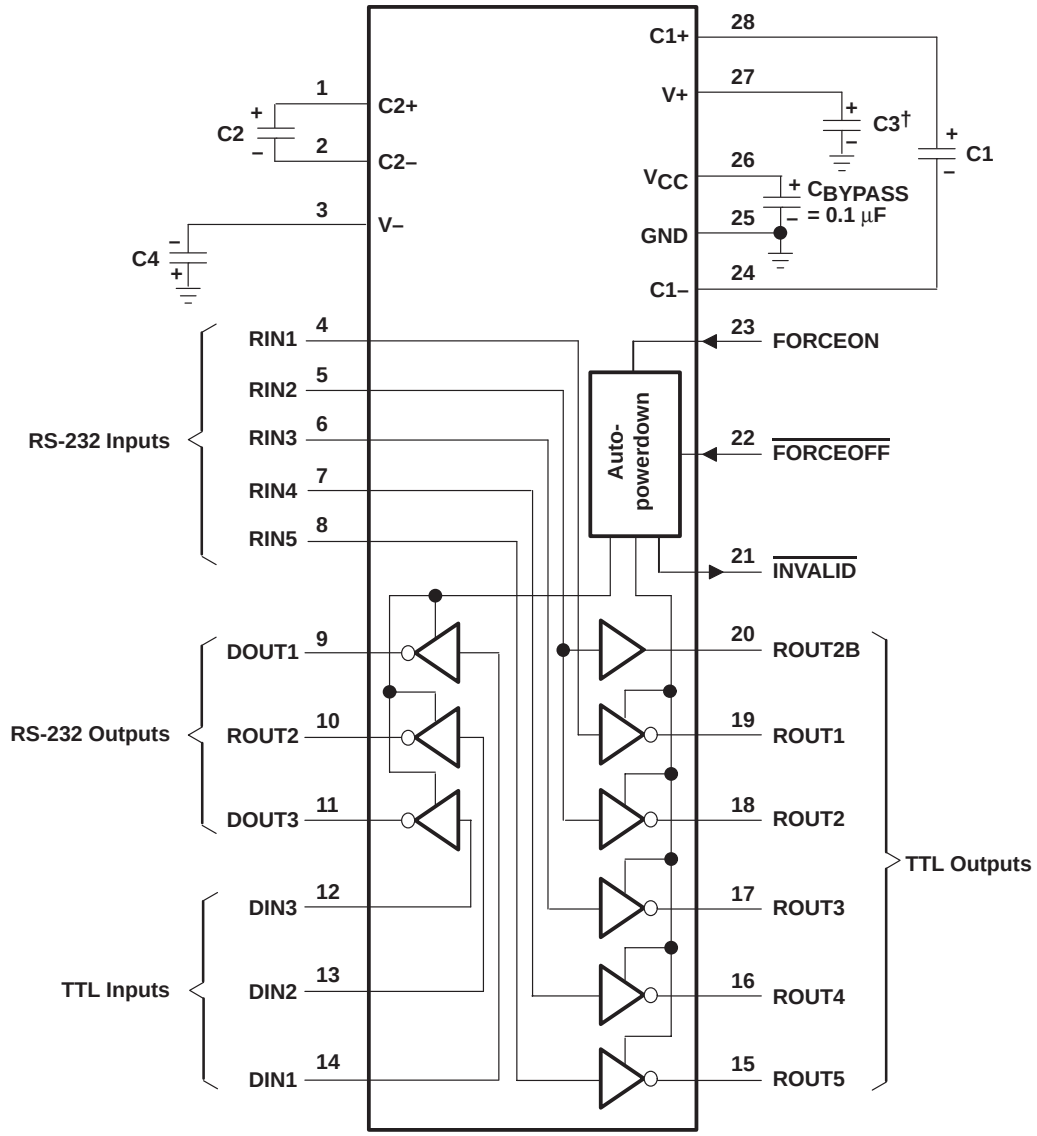


† Auto-powerdown disables drivers and reduces supply current to 1 μA.

NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 512 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 4. INVALID Propagation Delay Times and Driver Enabling Time

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V ± 0.3 V	0.1 μF	0.1 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.1 μF	0.47 μF

Figure 5. Typical Operating Circuit

PRODUCT PREVIEW

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